

Product Change Notification / JAON-04FTWF456

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11-Sep-2023

Product Category:

Power MOSFET Drivers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4540 Cancellation Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8900NC die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

Affected CPNs:

JAON-04FTWF456_Affected_CPN_09112023.pdf JAON-04FTWF456_Affected_CPN_09112023.csv

Notification Text:

PCN Status:Cancellation Notification

Microchip Parts Affected:This change would have affected selected products available in 8L SOIC package using 8900NC die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: This qualification was originally performed to qualify a new lead frame design for selected products available in 8L SOIC package using 8900NC die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

Impacts to Data Sheet:Not applicable

Change Impact: Not applicable

Reason for ChangeMicrochip has decided to not qualify the new lead frame design for selected products available in 8L SOIC package using 8900NC die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

Change Implementation Status: Not applicable

Estimated Qualification Completion Date: Not applicable

Revision History:February 9, 2021: Issued initial notification. September 11, 2023: Issued cancellation notification.

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

TC4427COA

TC427VOA

TC4427VOA

TC427EOA

TC4427EOA

TC427EOA713

TC4427EOA713

TC4427COA723

TC1427COA713

TC427COA713

TC4427COA713

TC4427COA713HAZ

TC427VOA713

TC4427VOA713

TC1428COA

TC428COA

TC4428COA

TC4428DCOA

TC428VOA

TC4428VOA

TC428EOA

TC4428EOA

TC428EOA713

TC4428EOA713

TC4428COA723

TC1428COA713

TC428COA713

TC4428COA713

TC428VOA713

TC4428VOA713

TC4426ACOA

TC4426AVOA

TC4426AEOA

TC4426AEOA713

TC4426ACOA713

TC4426AVOA713

TC4427ACOA

TC4427AVOA

TC4427AEOA

TC4427AEOAAAA

TC4427AEOA713

TC4427AEOA713AAA

TC4427ACOA713

TC4427AVOA713

TC4428ACOA

TC4428AVOA

Date: Monday, September 11, 2023

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TC4428AEOA713

TC4428ACOA713

TC4428ACOA713-GTD

TC4428AVOA713

TC1426COA

TC426COA

TC4426COA

TC4426VOA

TC426EOA

TC4426EOA

TC426EOA713

TC4426EOA713

TC1426COA713

TC426COA713

TC4426COA713

TC4426COA713CAA

TC4426VOA713

TC1427COA

TC427COA